

04-13-1999

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RE



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Patent and Trademark Office

101007621

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of Conveying Part(ies):

Werner Juengling  
Kevin G. Donohoe

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):

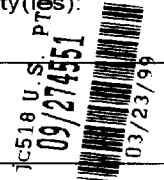
Name: Micron Technology, Inc.

Internal Address:

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83706-9632

Additional names(s) & address(es) attached:  Yes  No



Handwritten: 09-23-99

3. Nature of conveyance:

- Assignment  Security Agreement
- Merger  Change of Name
- Other \_\_\_\_\_

Execution Date: March 19, 1999

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: March 19, 1999

A. Patent Application No.(s):

B. Patent No.(s)

Additional numbers attached:  Yes  No

Additional numbers attached:  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David G. Latwesen, Ph.D.

Internal Address: Wells, St. John, Roberts,

Gregory & Matkin P.S.

Street Address: 601 W. First Avenue, Ste. 1300

City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved. . . . . 1

7. Total fee (37 CFR 3.41). . . . . \$40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number 23-0925

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David G. Latwesen, Ph.D.

Name of Person Signing

Signature

3/23/99

Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 5

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ASSIGNMENTPARTIES TO THE ASSIGNMENT:INVENTORS:

Werner Juengling

Kevin G. Donohoe

ASSIGNEE:

Micron Technology, Inc.  
Corporation of the State of Delaware  
8000 South Federal Way  
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTORS have conceived certain new and useful inventions disclosed in a United States patent application titled Methods Of Forming Materials Over Uneven Surface Topologies, And Methods Of Forming Insulative Materials Over And Between Conductive Lines.

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTORS hereby sell, assign and transfer to MICRON TECHNOLOGY, INC. the entire right, title and interest in the above-identified application executed currently

1 with this assignment and to any reissues, renewals, divisions or continuations  
2 thereof, and hereby authorizes the Commissioner of Patents and Trademarks  
3 to issue such Letters Patent to MICRON TECHNOLOGY, INC., for the sole  
4 use of MICRON TECHNOLOGY, INC., its successors or assigns.

5 INVENTORS further agree to execute, at the request and expense of  
6 MICRON TECHNOLOGY, INC. such other formal documents as may be  
7 required to fully convey the interest transferred herein and will similarly  
8 execute any application papers required for the filing of any division,  
9 continuation, renewal or reissue of the patent application or resulting Letters  
10 Patent; and will generally do everything necessary or desirable to obtain and  
11 enforce proper protection for the inventions assigned hereby.

12 INVENTORS further assign to MICRON TECHNOLOGY, INC. the  
13 whole right, title and interest in the inventions disclosed in the application  
14 throughout all countries foreign to the United States. MICRON  
15 TECHNOLOGY, INC. is hereby authorized to apply for patents relating to  
16 the inventions in its own name in countries where such procedure is proper;  
17 to claim the benefit of the International Convention; to file and prosecute  
18 International Applications relating to the inventions under the Patent  
19 Cooperation Treaty; and to file and prosecute applications relating to the  
20 inventions under the European Patent Convention. INVENTORS agree to  
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23 inventor, and to execute assignments of such applications and the resulting

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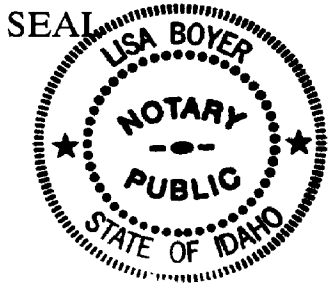
INVENTORS further warrant and covenant that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full rights to convey the same as herein expressed is possessed by the undersigned.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignees.

(Signature) Werner Juengling Date: 19-MAR-1999  
Werner Juengling

State of Idaho )  
County of Ada ) ss.

BEFORE ME, this 19 day of March 1999 personally appeared the above-named inventor, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her own free will for the purpose therein expressed.



Lisa Boyer  
Notary or Consular Officer  
My Commission Expires: 1-9-2002

1 (Signature)

Kevin G. Donohoe  
Kevin G. Donohoe

Date:

3/19/99

3 State of

Idaho

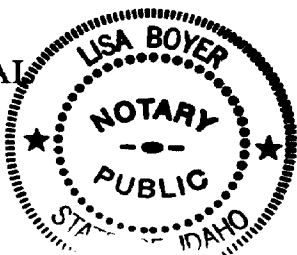
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8 SEAL



Lisa Boyer

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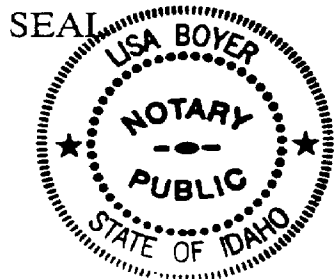
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20 Lisa Boyer  
21 Notary or Consular Officer  
22 My Commission Expires: 1-9-2002  
23



1 (Signature)

Kevin G. Donohoe  
Kevin G. Donohoe

Date:

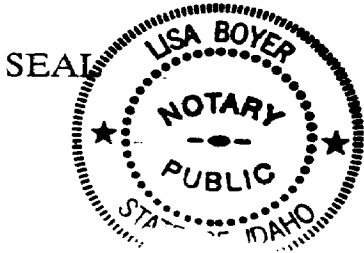
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